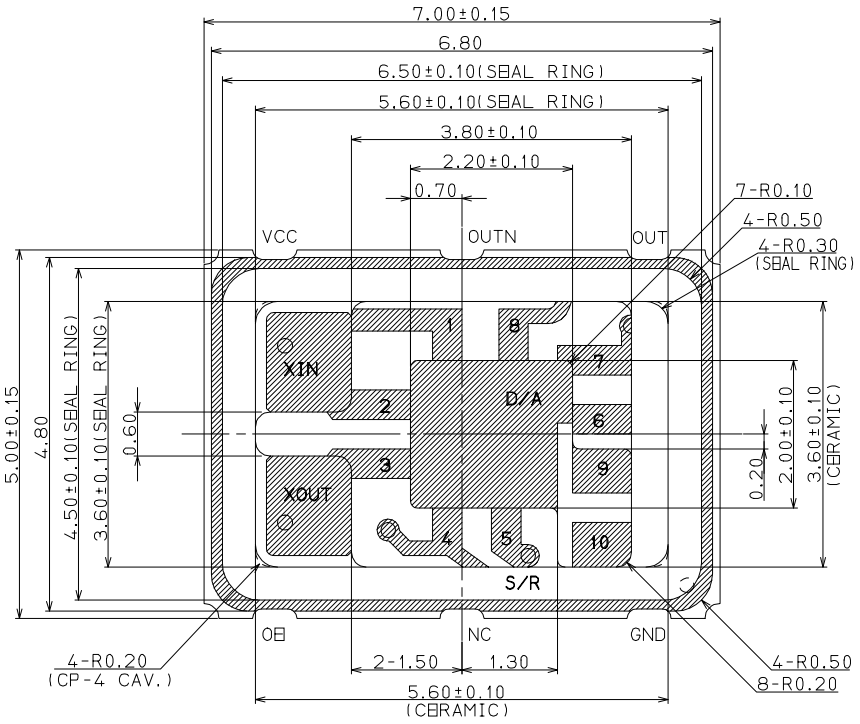

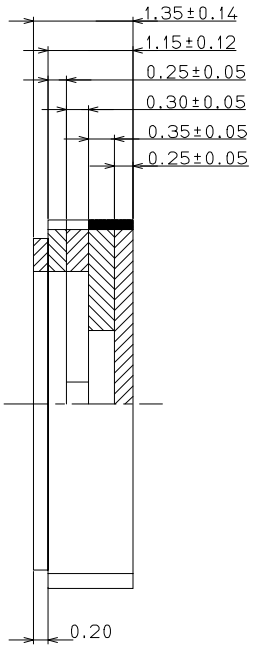

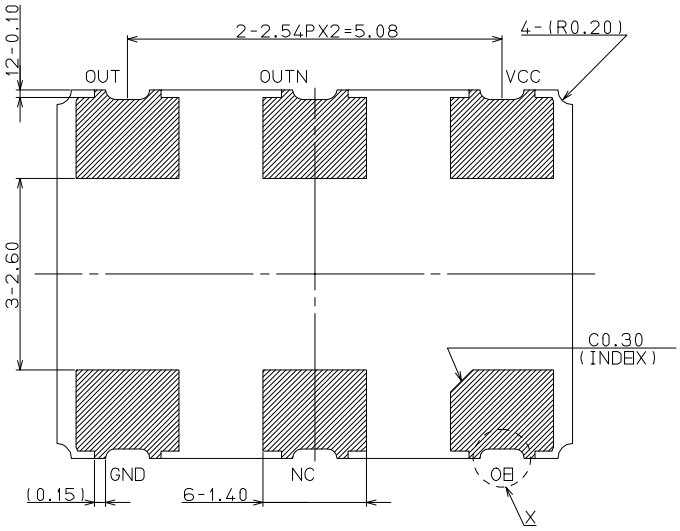

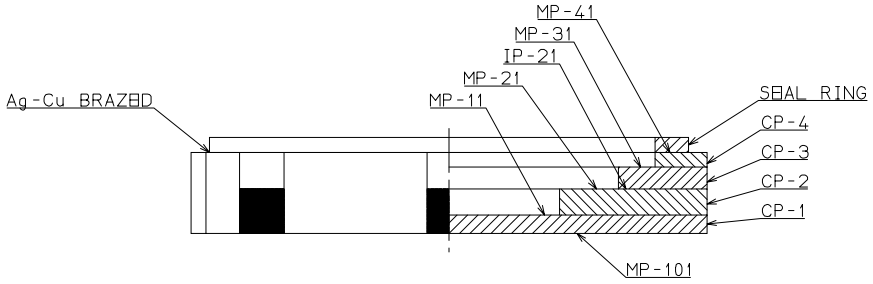

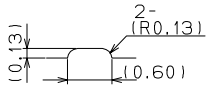

DETAIL X

NOTES:

1. PLATING THICKNESS:
   ELECTRO Ni : 1.27~8.89 MICRON. (SOLDER PADS)
   ELECTRO Au : 0.70~1.20 MICRON. (SOLDER PADS)
2. CONNECTION:
   (1-6-9-VCC),(2-XIN),(3-XOUT),(4-10-GND-S/R-D/A),
   (5-OE),(7-OUTN),(8-OUT),(NC-NC)
3. CAMBER : 50.00 MICRON MAX.
4. EXPOSURE OF CERAMIC SURFACE OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
5. ■ PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
6. STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
7. SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

TOLERANCE: ±1% N.L.T.±0.13 ANGLES	REVISION: SEE ATTACHED EXCEPTIONS SHEET.				TITLE: CF5034 PKG
MATERIAL: 90%MIN.Al2O3 (NA-311B BLACK)	SCALE: 15 : 1	DIMENSION: mm	PROJECTION: 3rd	CUSTOMER DWG NO. / REV.	PART NO.: S5070DCK1 / REV.: 0
	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED
	Shigetomi	Kawamura	Ohba	Kumura	Sugi
	Sep.12.02	Sep.12.02	Sep.12.02	Sep.12.02	Sep.12.02
					DWG NO. / SHT/OF: 1/7

Sumitomo Metal (SMI) Electronics Devices Inc.